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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16691**Generic Copy

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**Issue Date:** 26-Jul-2011

**TITLE:** Final Notification for Transfer of Zener Filtering products from Hynix (Magna Chip) in Korea to ON Semiconductor Pocatello (ID) in United State.

**PROPOSED FIRST SHIP DATE:** 26-Oct-2011 or earlier with customer approval.

**AFFECTED CHANGE CATEGORY(S):** ON Semiconductor Fab Site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or YEW HEE SOON <[y.soon@onsemi.com](mailto:y.soon@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or Francis Lualhati  
<[francis.lualhati@onsemi.com](mailto:francis.lualhati@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor is notifying customers of its plan to transfer fabrication of Zener ESD Protection products from Hynix (Magna Chip) located in Seoul, South Korea, to ON Semiconductor Fab 10 located in Pocatello, ID (USA).

Description of the change:

The transfer and qualification of the Zener Z2B process and the associated integrated circuits from the Hynix (Magna Chip) facility (South Korea) to the Fab 10 wafer fabrication site located in the Pocatello, Idaho.

The Fab 10 facility is an ON Semiconductor owned wafer fab that has been producing products since 2000 (formerly as AMI). Several existing technologies within ON Semiconductor's product families are currently sourced from Fab 10, including CMOS and LVFR products. The Fab 10 Pocatello site is certified according to ISO9001:2008, 14001:2004, ISO/TS 16949:2009 and AS 9100B standards as well as MIL-PRF-38535, CTPAT and STACK.

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Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

Devices listed in this final PCN should be transferred to ON Semiconductor Fab 10 in Pocatello starting Oct 2011. After 28 Oct 2011, customer may receive devices from either facility. Parts are identifiable by date code 1143 (YYWW).

**RELIABILITY DATA SUMMARY:**

Package: CSP  
Qual Vehicles: CM6100

**Qualification Results and Analysis:**

Test:	Conditions:	Interval:	Results
HTRB	TA=125°C, V=5.5 Volts	1008 hrs	0/240
HTSL	TA = 150°C	1008 hrs	0/240
UHASt	Ta=130C RH=85%, unbiased	1008 hrs	0/240
TC	Ta= -40 C to 125 C	500 cyc	0/239
Autoclave	Ta=121C RH=100% ~15 psig	96 hrs	0/240
ESD IEC61000-4-2, Contact Discharge	± 8KV min		± 14KV
ESD IEC61000-4-2, Air Discharge	± 15KV min		± 16KV

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Available upon request

**CHANGED PART IDENTIFICATION:**

There will be no changes to standard device markings. Normal assembly lot traceability codes will identify the wafer fab source.

**List of affected General Parts:**

CM6100